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ZXTD617MC

DUAL 15V NPN LOW SATURATION TRANSISTORS

Features and Benefits

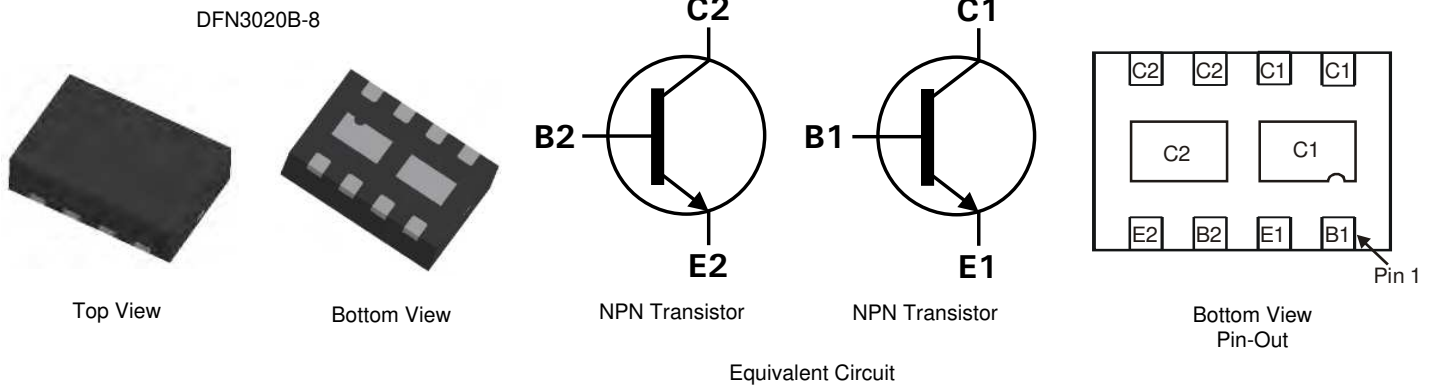
- $BV_{CEO} > 15V$
- $I_C = 4.5A$ Continuous Collector Current
- Low Saturation Voltage (100mV max @ 1A)
- $R_{SAT} = 45 m\Omega$ for a Low Equivalent On-Resistance
- h_{FE} specified up to 12A for high current gain hold up
- Dual NPN saving footprint and component count
- Low profile 0.8mm high package for thin applications
- $R_{\theta JA}$ efficient, 40% lower than SOT26
- 6mm² footprint, 50% smaller than TSOP6 and SOT26
- **Lead-Free, RoHS Compliant (Note 1)**
- **Halogen and Antimony Free. "Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: DFN3020B-8
- Case Material: Molded Plastic. "Green" Molding Compound.
- Terminals: Pre-Plated NiPdAu leadframe
- UL Flammability Rating 94V-0
- Nominal Package Height: 0.8mm
- Moisture Sensitivity: Level 1 per J-STD-020
- Weight: 0.013 grams (approximate)

Applications

- DC-DC Converters
- Charging circuits
- Motor control
- Power switches
- Portable applications



Ordering Information

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTD617MCTA	DAA	7	8	3000

- Notes:
1. No purposefully added lead.
 2. Diodes Inc's "Green" Policy can be found on our website at <http://www.diodes.com>

Marking Information



DAA = Product type marking code
Top view, dot denotes pin 1

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

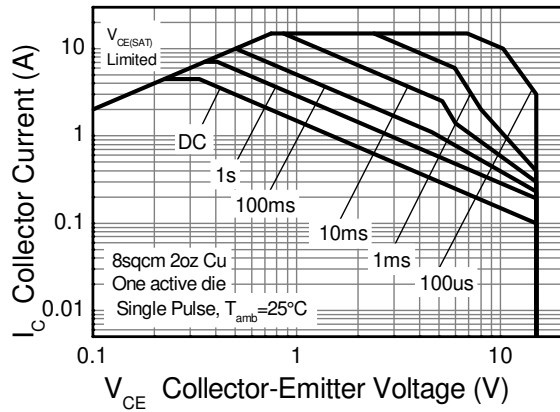
Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	40	V
Collector-Emitter Voltage	V_{CEO}	15	
Emitter-Base Voltage	V_{EBO}	7	
Peak Pulse Current	I_{CM}	15	A
Continuous Collector Current	I_C	(Notes 3 & 6) 4.5	
		(Notes 4 & 6) 5	
Base Current	I_B	1	

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

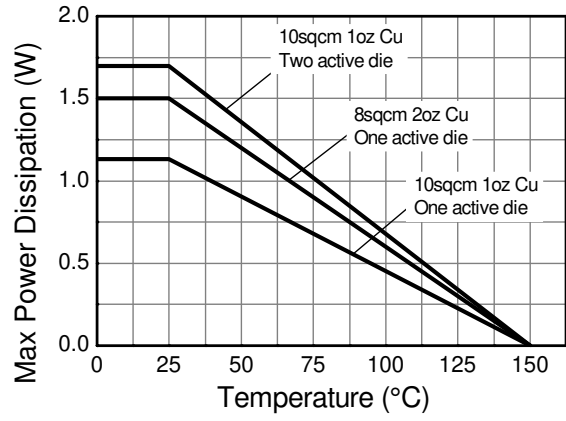
Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor	P_D	(Notes 3 & 6) 1.5	W mW/ $^\circ\text{C}$
		(Notes 4 & 6) 12	
		(Notes 5 & 6) 2.45	
		(Notes 5 & 7) 19.6	
		(Notes 5 & 7) 1.13	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	(Notes 5 & 7) 8	$^\circ\text{C/W}$
		(Notes 3 & 6) 1.7	
		(Notes 4 & 6) 13.6	
		(Notes 5 & 6) 83.3	
Thermal Resistance, Junction to Lead	$R_{\theta JL}$	(Notes 5 & 7) 51.0	$^\circ\text{C/W}$
		(Notes 6 & 8) 111	
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

- Notes:
3. For a dual device surface mounted on 28mm x 28mm (8cm²) FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions; the device is measured when operating in a steady-state condition. The heatsink is split in half with the exposed collector pads connected to each half.
 4. Same as note (3), except the device is measured at $t < 5$ sec.
 5. Same as note (3), except the device is surface mounted on 31mm x 31mm (10cm²) FR4 PCB with high coverage of single sided 1oz copper.
 6. For a dual device with one active die.
 7. For dual device with 2 active die running at equal power.
 8. Thermal resistance from junction to solder-point (at the end of the collector lead).

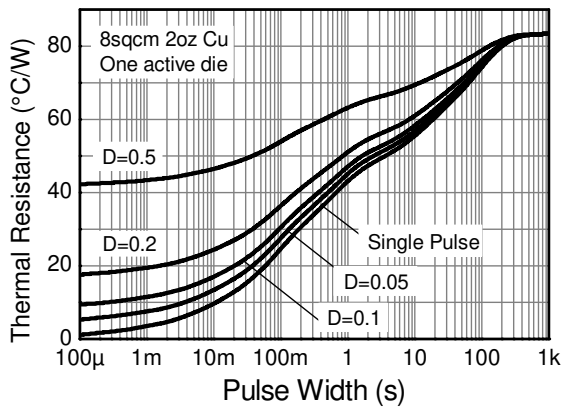
Thermal Characteristics



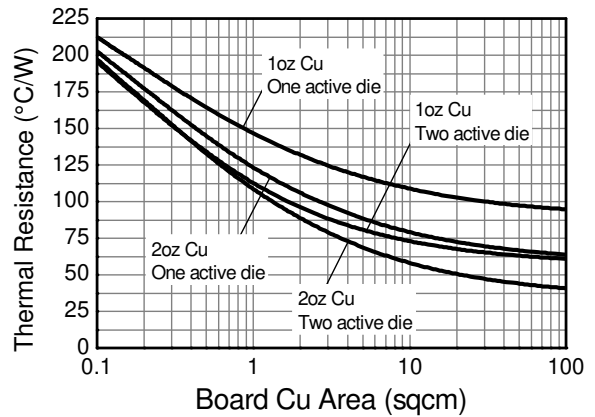
Safe Operating Area



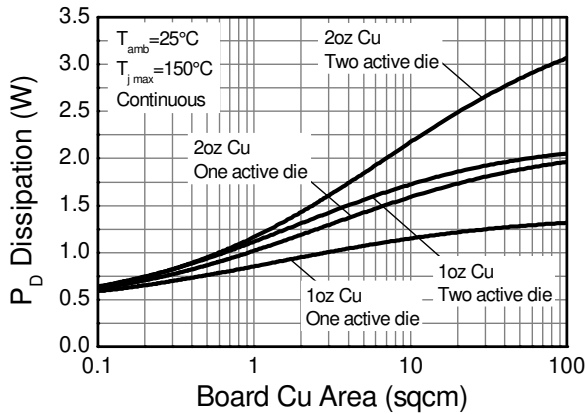
Derating Curve



Transient Thermal Impedance



Thermal Resistance v Board Area



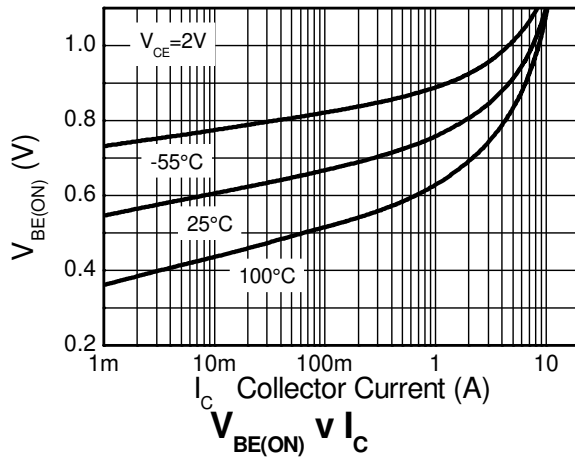
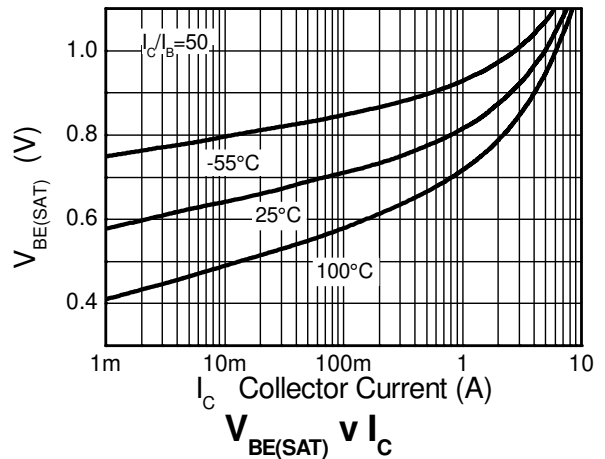
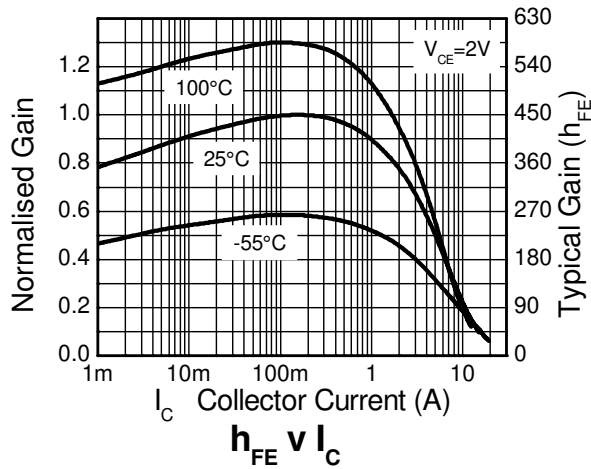
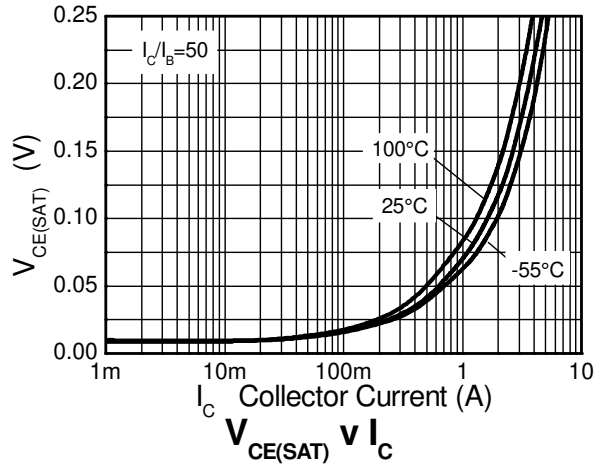
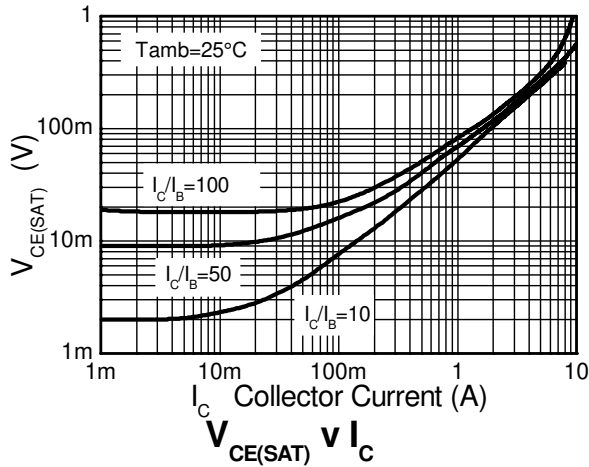
Power Dissipation v Board Area

Electrical Characteristics @T_A = 25°C unless otherwise specified

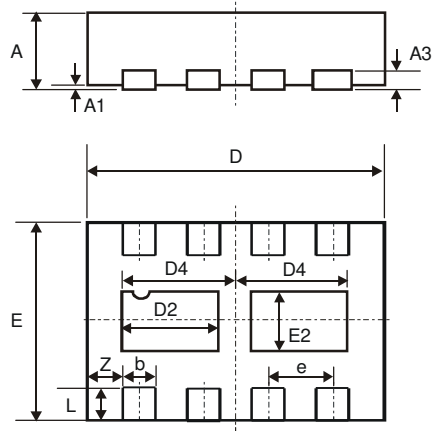
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	40	70	-	V	I _C = 100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	15	18	-	V	I _C = 10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	7	8.2	-	V	I _E = 100μA
Collector Cutoff Current	I _{CBO}	-	-	100	nA	V _{CB} = 30V
Emitter Cutoff Current	I _{EBO}	-	-	100	nA	V _{EB} = 6V
Collector Emitter Cutoff Current	I _{CES}	-	-	100	nA	V _{CES} = 12V
Static Forward Current Transfer Ratio (Note 9)	h _{FE}	200	415	-	-	I _C = 10mA, V _{CE} = 2V
		300	450	-	-	I _C = 200mA, V _{CE} = 2V
		200	320	-	-	I _C = 3A, V _{CE} = 2V
		150	240	-	-	I _C = 5A, V _{CE} = 2V
		-	80	-	-	I _C = 12A, V _{CE} = 2V
Collector-Emitter Saturation Voltage (Note 9)	V _{CE(sat)}	-	8	14	mV	I _C = 0.1A, I _B = 10mA
		-	70	100	mV	I _C = 1A, I _B = 10mA
		-	165	200	mV	I _C = 3A, I _B = 50mA
		-	240	310	mV	I _C = 4.5A, I _B = 50mA
		-	200	-	mV	I _C = 4.5A, I _B = 100mA
Base-Emitter Turn-On Voltage (Note 9)	V _{BE(on)}	-	0.88	0.96	V	I _C = 4.5A, V _{CE} = 2V
Base-Emitter Saturation Voltage (Note 9)	V _{BE(sat)}	-	0.94	1.05	V	I _C = 4.5A, I _B = 50mA
Output Capacitance	C _{obo}	-	30	40	pF	V _{CB} = 10V, f = 1MHz
Transition Frequency	f _T	80	120	-	MHz	V _{CE} = 10V, I _C = 50mA, f = 100MHz
Turn-on Time	t _{on}	-	120	-	ns	V _{CC} = 10V, I _C = 1A
Turn-off Time	t _{off}	-	160	-	ns	I _{B1} = I _{B2} = 10mA

Notes: 9. Measured under pulsed conditions. Pulse width ≤ 300 μs. Duty cycle ≤ 2%

Typical Electrical Characteristics

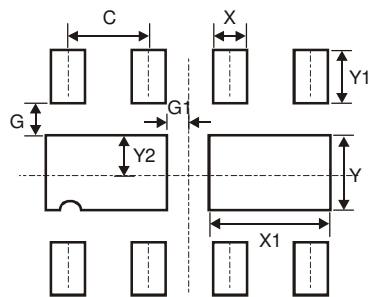


Package Outline Dimensions



DFN3020B-8			
Dim	Min	Max	Typ
A	0.77	0.83	0.80
A1	0	0.05	0.02
A3	-	-	0.15
b	0.25	0.35	0.30
D	2.95	3.075	3.00
D2	0.82	1.02	0.92
D4	1.01	1.21	1.11
e	-	-	0.65
E	1.95	2.075	2.00
E2	0.43	0.63	0.53
L	0.25	0.35	0.30
Z	-	-	0.375
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
C	0.650
G	0.285
G1	0.090
X	0.400
X1	1.120
Y	0.730
Y1	0.500
Y2	0.365

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